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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Charles W.C. Lin

Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA

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ASSISTANT COMMISSIONER FOR PATENTS

Washington, D.C. 20231

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**INFORMATION DISCLOSURE STATEMENT**

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98, Applicant hereby provides a copy of the documents identified on the enclosed Form PTO-1449.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Accordingly, no fee is due. 37 C.F.R. § 1.97(b)(3).



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